

Gas Plasma Dry Cleaner

Plasma Surface Treatment Device

PDC200/210/510

High frequency output	300W (PDC200)	500W (PDC210/510)	Stage size	250×170mm (PDC200/210)	410×210mm (PDC510)
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Small and compact, suitable for R&D purposes

Features

- Simple and compact plasma surface treatment device
- RIE (Reactive Ion Etching) Plasma mode, with DP (Direct Plasma) mode as option
- Excellent electrode structure for plasma uniformity
- Simple touch panel system

Applications

- Plasma processing of CSP, BGA, COB substratum
- Removal of organic films and metal oxidized films
- Dry cleaning of printed circuit board
- Surfactant process
- LED assembly
- For R&D

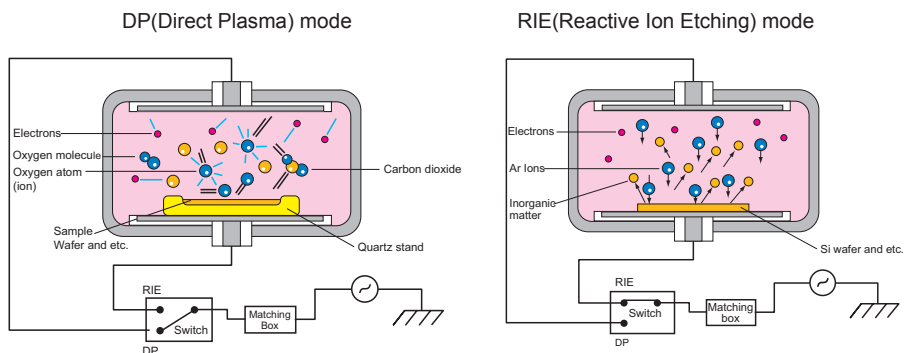


PDC210

Chamber



Diagram



Specifications

Model	PDC200	PDC210	PDC510
Plasma mode	RIE (DP mode option)		RIE/DP selectable
Electrode structure	Parallel flat stage plate		
Vacuum gauge	Capacitance manometer		
High frequency output	Max 300W	Max 500W	
Oscillation frequency	13.56MHz Quartz oscillator		
Output setting method	Manual setting on LCD touch panel		
Matching method	Auto tuning		
Controller	Programmable		
Display	LCD touch panel		
Chamber size	W400 × D250 × H150mm		W500 × D300 × H200mm
Stage size	W250 × D170mm		W410 × D210mm
Chamber material	Aluminum		
Reaction gas	2 systems (Argon, Oxygen)		
Purge gas	Nitrogen or dry air		
Reaction gas flow control	Flow meter	Mass flow controller	
Rotary vacuum pump (optional)	~345L/min.		~500L/min.
External dimensions	W540×D600×H600mm	W540×D600×H600mm	W700×D700×H700mm
Weight	~100kg	~105kg	180kg
Power source	Single phase AC115V 50/60Hz	3-phase AC200V~AC240V 50/60Hz	